

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Shui-Ming Cheng</td><td>08/30/2004</td></tr><tr><td>Hung-Wei Chen</td><td>08/30/2004</td></tr><tr><td>Zhong Tang Xuan</td><td>08/30/2004</td></tr></tbody></table>		Name	Execution Date	Shui-Ming Cheng	08/30/2004	Hung-Wei Chen	08/30/2004	Zhong Tang Xuan	08/30/2004
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Shui-Ming Cheng	08/30/2004								
Hung-Wei Chen	08/30/2004								
Zhong Tang Xuan	08/30/2004								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Rd. 6								
Internal Address:	Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>10916023</td></tr></tbody></table>		Property Type	Number	Application Number:	10916023				
Property Type	Number								
Application Number:	10916023								
CORRESPONDENCE DATA									
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Total Attachments: 2 source=assignment#page1.tif source=assignment#page2.tif									

CH \$40.00 10916023

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---|
| (1) | Shui-Ming Cheng | of | No. 12-24, Lin 7, Chu-Bai Li
Hsin-Chu 302, Taiwan, R.O.C. |
| (2) | Hung-Wei Chen | of | 14F-3, No. 68, Ta-Hsueh Road
Hsin-Chu City 300, Taiwan, R.O.C. |
| (3) | Zhong Tang Xuan | of | 5F-2, No. 5, Lane 129
Heping 1 st Rd, Lingya District
Kaohsiung City 802, Taiwan, R.O.C. |

have invented certain improvements in

**SEMICONDUCTOR DEVICE HAVING HIGH DRIVE CURRENT
AND METHOD OF MANUFACTURE THEREOF**

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on August 11, 2004 and assigned application number 10/916023; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2003.0959/24061.221/.222

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Shui-Ming ChengResidence Address: No. 12-24, Lin 7, Chu-Bai Li
Hsin-Chu 302, Taiwan, R.O.C.
Taiwan, R.O.C.Dated: ✓ 08/30/2004Shui Ming Cheng
Inventor Signature

Inventor Name: Hung-Wei ChenResidence Address: ~~6F, No. 13, Fu-Gyun Street~~ 14F-3, No. 6F, Ta-Hsueh Road,
Hsin-Chu City 300, Taiwan, R.O.C.
Taiwan, R.O.C.Dated: ✓ 08/30/2004✓ Hung-Wei Chen
Inventor Signature

Inventor Name: Zhong Tang XuanResidence Address: ✓ 5F-2, No. 4, Lane 129, Heping 1st Rd, Lingya
District, Kaohsiung City 802, Taiwan (R.O.C)
Taiwan, R.O.C.Dated: ✓ 08/30/2004✓ Zhong Tang Xuan
Inventor Signature

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